BAREBONE
XPC slim
DH810

ROBUST AND POWERFUL 1.3-LITRE SLIM PC SUPPORTS INTEL CORE ULTRA 200 SERIES PROCESSORS

This robust 1.3-litre Barebone PC houses the performance of Intel's Core Ultra 200 series processors (Socket LGA1851 "Arrow Lake-S") with Integrated Neural Processing Unit (NPU) for demanding AI workloads. The DH810 supports up to 8K display resolution via HDMI 2.1 plus two independent DisplayPorts (one as USB-C), delivering a stunning visual experience for digital signage and entertainment. Beside this it also offers Dual Intel LAN, eight additional USBs and two COM ports. The slim metal chassis comes with a VESA mount included, provides versatile connectivity and reliable operation in environments with ambient temperatures of up to 50 °C. This platform is targeted at professional applications such as AI tasks, Digital Signage, POS, POI, gambling machines, office, healthcare and industry.

Max. 96 GB DDR5 · HDMI 2.1 8K SUPPORT · DISPLAY-PORT 1.4a · USB-C with DP and USB4 · NVMe SSD SUPPORT · 2.5" HDD/SSD SUPPORT · DUAL LAN (2.5G + 1.0G) · DUAL COM · VESA MOUNT INCLUDED · WLAN / LTE OPTIONAL · Max. 50 °C · 24/7 SUPPORT

SLIM DESIGN
■ Slim 1.35-litre metal chassis, black ■ Dimensions: 190 x 165 x 43 mm (LWH) ■ Including VESA mount (75/100 mm) ■ Supports 24/7 Nonstop Operation ■ Operating temperature: 0~50 °C (non-condensing)

OPERATING SYSTEM
■ An operating system is not included
■ Supports Windows 11 and Linux (64-bit)

PROCESSOR SUPPORT
■ Socket LGA1851 supports Intel Core Ultra 200 series 9/7/5 processors (code name "Arrow Lake-S"), max. 65W TDP
■ Advanced heatpipe cooling system with two 70 mm fans

GRAPHICS
■ Integrated Intel Xe series graphics, 4K/8K support (features depend on processor) ■ Supports three independent UHD displays

CHIPSET
■ Intel H810 Chipset

MEMORY SUPPORT
■ 2x 262-pin SO-DIMM slot ■ Supports DDR5-5600
■ max. 2x 48 GB = 96 GB in total

STORAGE – SATA / M.2
■ 1x 2.5" bay for SATA hard disk or SSD ■ 1x M.2-2280M slot (supports PCIe 4.0 x4 NVMe or SATA) ■ 1x M.2-2230E for optional WLAN module

CONNECTORS
■ HDMI 2.1 (supports 8K / 60 Hz) ■ DisplayPort 1.4a ■ USB-C supports DisplayPort, USB4 and 3A charging) ■ optional VGA
■ 2x USB 3.2 Gen2 (1x Type-C) ■ 2x USB 3.2 Gen1 ■ 4x USB 2.0
■ 2x Intel LAN (1G + 2.5G) ■ 2x COM port (1x RS232/422/485)
■ "Always on" Jumper ■ 2x Audio (line out, mic-input)
■ Connector for external power button

POWER SUPPLY
■ External 120W/19V power adapter (DC Input supports 12V and 19V)

OPTIONAL ACCESSORIES
■ WLAN-ax Kit (WLN-M1) ■ Vertical Stand (PS02) ■ VGA Port (PVG01)
■ Rackmount kit (PRM01) ■ Cable for external power button (CXP01)
■ DIN-Rail mounting kit (DIR01) ■ 4G/LTE-kit (WWN03)

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Shuttle XPC slim PCs with Intel 800 series chipset

Product	Vol.	PCIe Slots	Chip	HDMI 2.x	DP 1.4a	DP 1.4a/ USB4	VGA Port	max. Displays	LAN (Intel)	M.2 SSD Gen4/5	USB 3.2 Gen2/1	USB 2.0	COM Port	Pwr Adap.	DC-In	VESA Mount
DH810S	1.35 L	—	H810	1	2	—	opt.	3	1G	1 / 0	2+2	4	1	120W	12V+19V	incl.
DH810	1.35 L	—	H810	1	1	1	opt.	3	1G+2.5G	1 / 0	2+2	4	2	120W	12V+19V	incl.
DB860	1.35 L	—	B860	2	1	1	opt.	4	1G+2.5G	0 / 1	4+4	0	2	180W	12V+19V	incl.
XH810	3.5L	X16	H810	2	1	—	opt.	3	1G+2.5G	2 / 0	2+2	4	3	120W	12V+19V	incl.
XB860G2	4.5L	X16+X1	B860	2	1	—	opt.	4	1G+2.5G	2 / 1	2+4	2	0	180W	19V	incl.

PRODUCT FEATURES

Height: 4.3 cm only

Robust, stylish and particularly small

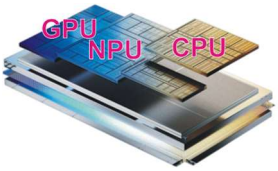
You should have held it in your own hands to see how small it actually is. At barely a volume of 1.35 litres, its steel chassis gives it the appropriate stability required for professional applications such as digital signage. Despite its dimensions of 19 x 16.5 x 4.3 cm (LWH), the overall system performance is very high thanks to support of Intel Core desktop processors. The interior of the DH810 is very tidy too so that it won't take long to set up. Its sleek and stylish looks let it easily find a place in both home and office environments.

Low noise thanks to heatpipe cooling system

An efficient heatpipe cooling system with two 70 mm fans ensures whisper-quiet operation and system stability.

Supports extended temperature range and 24/7 operation

The Shuttle XPC slim Barebone DH810 is officially approved for 24/7 permanent operation. Thanks to its efficient cooling, this PC runs highly reliably making it perfectly suitable for digital signage and POI/POS applications – even at ambient temperatures of up to 50 °C (non-condensing).
Caution: For high ambient temperatures over 40 °C we strongly recommend to use SSDs.



Supports Socket LGA1851 Intel® Core™ Ultra processors

"Arrow Lake-S" is the codename for Intel's Core Ultra 200 series Generation of Intel® Core™ Ultra Desktop Processors for socket LGA1851 introduced along with the 800-Series chipsets. These processors feature up to 24 cores (8 Performance-cores and 16 Efficient-cores), up to 4 Intel Xe graphics cores and integrates a Neural Processing Unit (NPU).

TRIPLE Display support and 8K

The DH810 features three digital video outputs: one HDMI 2.1 which can even support 8K/60Hz resolution, and two DisplayPorts 1.4a – one of which as USB-C. Furthermore, the DH810 supports an optional D-Sub/VGA port. The PC supports a maximum of three displays.

One M.2-Slot for SSD cards

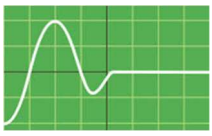
The M.2-2280 slot supports one M.2 SSD storage card with NVMe PCIe 4.0 X4 or SATA interface. A heat sinks kit with thermal pads for efficient cooling are included.

Dual Intel LAN Network

The Shuttle XPC slim Barebone DH810 supports 2.5G and 1.0G LAN with Intels 226 and 219 network adapters, which are popular for their excellent performance and driver compatibility and are the preferred choice for professional environments.

VESA mount

The supplied 75/100mm VESA mount allows for installation on to walls or monitors which is particularly interesting for the industry segment, company buildings and public institutions. Other than this, the chassis bears numerous threaded holes (M3) enabling it to be fitted almost anywhere.

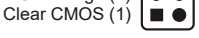


Power on after Power fail

The BIOS setup provides a "Power-On after Power Fail" function that can be found under "Power Management Configuration". As the name indicates, this function determines the PC's behaviour after power failure: (1) unconditional power on, (2) restore former status (3) keep system turned off (4) Power-On by LAN or (5) Power-On by Real-Time-Clock. As a matter of the nature of this function, it may fail after short power failures. This is why the DH810 also comes with a hardware-based solution. By removing Jumper JP1 (see image) the system will start unconditionally once power is applied.

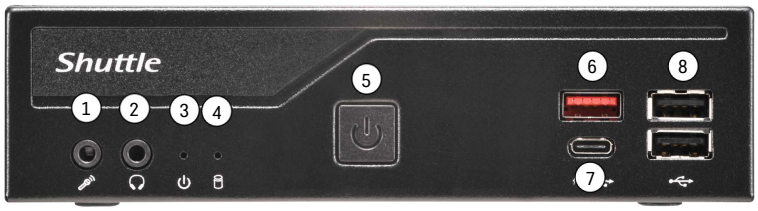
External power button by separate remote line

If, because of space constraints (e.g. in case of fixed installation), the machine cannot be switched on by pressing the front power button, it can be powered on by a separate remote line. You will find an appropriate four-pin connector at the back panel of the DH810 (pitch 2.54 mm). Furthermore, this connector provides a Clear CMOS function and +5V DC voltage supply for external devices.

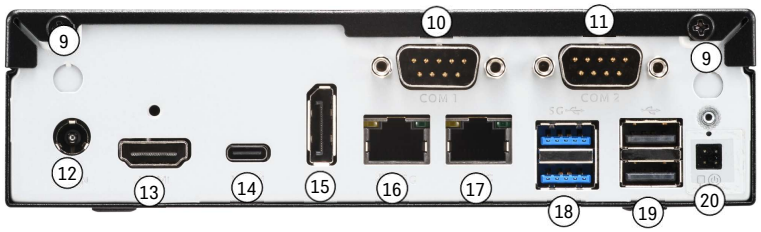


Front and Back Panel

Front Panel



Back Panel



Side View

VESA Mount

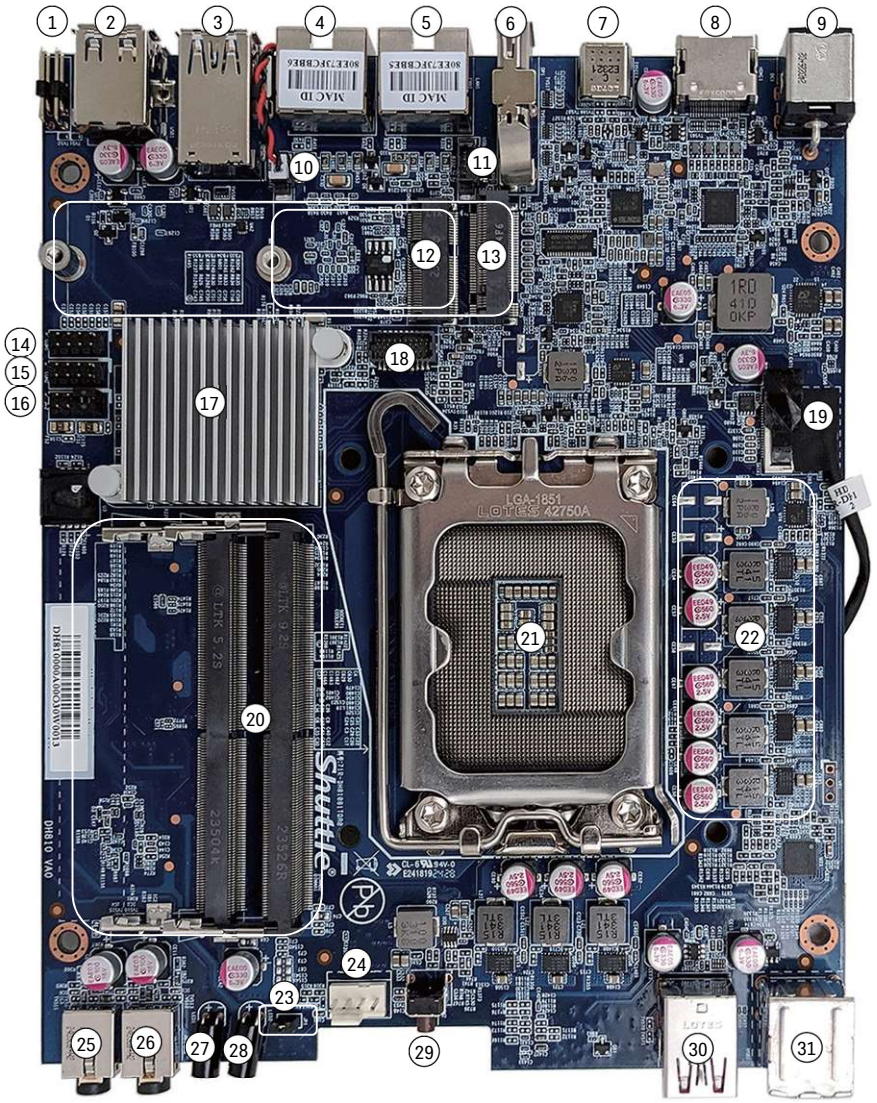
1. Microphone input
2. Headphones output
3. LED indicator for power state
4. LED indicator for storage activity
5. Power button
6. 1x USB 3.2 Gen 2 port (Type-A)
7. 1x USB 3.2 Gen 2 port (Type-C), supports 3A charging
8. 2x USB 2.0 (Type-A)
9. 2x WLAN perforation
10. COM 1 port supports RS232/RS422/RS485
11. COM 2 port supports RS232 (or optional VGA port for analog displays)
12. DC-in connector for power adapter supports 12V and 19V
13. 1x HDMI 2.1 port (supports 8K / 60 Hz)
14. USB4/20 Gbps (USB-C), also supports DisplayPort 1.4a and 3A charging
15. DisplayPort 1.4a
16. RJ45 2.5G LAN port (Intel 226)
17. RJ45 Gigabit LAN port (Intel 219)
18. 2x USB 3.2 Gen 1 port (Type-A)
19. 2x USB 2.0 (Type-A)
20. 4-pin connector (2.54 mm pitch) for external power button, Clear CMOS button and 5V DC voltage

21. Threaded holes (M3)
22. 2x hole for Kensington Lock

23. VESA mount (two parts)

Mainboard

Back panel



Front panel

Back view

Front view

1. 4-pin connector (2.54 mm pitch) for external power button, Clear CMOS button and 5V DC voltage
2. 2x USB 2.0 port
3. 2x USB 3.2 Gen 1 port (blue)
4. RJ45 1.0G LAN port (Intel 219)
5. RJ45 2.5G LAN port (Intel 226)
6. DisplayPort (DP 1.4a)
7. USB-C supports DP 1.4a, USB4 and 3A charging
8. HDMI 2.1 port
9. DC-in connector for power adapter
10. Connector for CMOS battery
11. Onboard USB 2.0 connector (4-pin)
12. M2-2230E slot for WLAN card
13. M.2-2280M slot for SSD card
14. Onboard COM 1 port supports RS232/RS422/RS485
15. Onboard COM 2 port supports RS232
16. Jumper for COM 1/2 auxiliary voltage setting (0/5/12 V)
17. Intel H810 chipset with heat sink
18. Onboard VGA connector
19. SATA v3.0 connector
20. 2x SO-DIMM slot for DDR5 memory
21. LGA1851 processor socket
22. CPU Voltage Regulator
23. Always-Power-On jumper (JP1)
24. 4-pin connector for cooling fan
25. Microphone input
26. Headphones output
27. LED indicator for power state
28. LED indicator for storage activity
29. Power button
30. 2x USB 3.2 Gen 2 port (1x Type-A red, 1x Type-C)
31. 2x USB 2.0

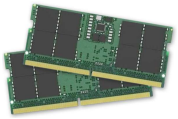
REQUIRED COMPONENTS

The following components need to be added to make it a fully-configured Mini PC

Shuttle XPC slim Barebone DH810

LGA1851 Processor

Intel Core Ultra 5/7/9 - 200 series “Arrow Lake-S”
TDP max. 65 W



Memory Modules

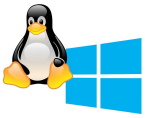
Up to two DDR5-5600 (or higher)
SO-DIMM memory modules max. 48 GB each
Total capacity: 96 GB

2.5" Storage Drive

SATA hard disk or Solid State Disk (SSD)
(max. height: 12.5 mm)

M.2 SSD

M.2-2280 SSD storage (SATA or PCIe/NVMe)



Operating System

Windows 11 or Linux (64-bit only)

OPTIONAL ACCESSORIES FROM SHUTTLE

VGA port adapter **PVG01**

Installing PVG01 means one serial port (COM) less can be used on the backpanel.

WLAN-Accessory **WLN-M1**

M.2-2230 card supports WLAN-ax (Wi-Fi 6) and Bluetooth. Including 2 antennas.

LTE Adapter Kit **WWN03**

allows the installation of an M.2 LTE card and nano SIM card (occupies the 2.5” bay)

Cable **CXP01**

Cable for external push button switch (without button)

Vertical Stand **PS02**

for vertical operation

DIN-Rail Kit **DIR01**

This mounting kit allows the installation on a standard 35 mm DIN-Rail

Rack Mount Kit **PRM01**

2U front plate to install two 1.3L Shuttle XPCs in a 19" cabinet.

Product Comparison: Shuttle XPC slim 1.3L PCs with Intel 6xx/7xx/8xx chipsets

Model	DH610S	DH610	DH670	DH670V2	DH770	DH810	DB860
Processor Support	Intel Core, Socket LGA1700, TDP max. 65 W Code name "Alder Lake-S"/"Raptor Lake-S (Refresh)" – Gen 12/13/14					Intel Core Ultra, Socket LGA1851 max. 65 W, Code name "Arrow Lake-S"	
Cooling	Heat-pipe with 2x 60 mm Fan				Heat-pipe with 2x 70 mm Fan		
Chipset	Intel H610	Intel H610	Intel H670	Intel H670	Intel H770	Intel H810	Intel B860
OS Support	Windows 10/11 and Linux (64-bit)					Windows 11 and Linux (64-bit)	
Display Supp.	max. 2 *)	max. 3	max. 4	max. 4	max. 4	max. 3	max. 4
SO-DIMM RAM Slots	max. 2x 32 GB DDR4-3200/2666				max. 2x 32 GB DDR5-5600	max. 2x 48 GB DDR5-5600	
2.5" bay	1x 2.5" drive bay, SATA connector, max. height 12.5 mm						
M.2-2280 SSD Slot	1x PCIe 3.0/SATA	1x PCIe 3.0/SATA	1x PCIe 4.0/SATA	1x PCIe 4.0/SATA	1x PCIe 4.0/SATA	1x PCIe 4.0/SATA	1x PCIe 5.0/SATA
WLAN Slot	M.2-2230E						
Buttons/LED	Power-Button, Power LED, HDD LED						
Card Reader	No	No	Yes	No	No	No	No
Graphics Ports	HDMI 2.0b DP 1.4	HDMI 2.0b 2x DP 1.4	2x HDMI 2.0b 2x DP 1.4	2x HDMI 2.0b 2x DP 1.4	2x HDMI 2.0b 2x DP 1.4	1x HDMI 2.1 1x DP 1.4a 1x USB4 (DP, 3A)	1x HDMI 2.1 1x HDMI 2.0 1x DP 1.4a 1x USB4 (DP, 3A)
USB 3.2 Gen2	–	–	4	4	4	2 (1x Type-C)	4 (1x Type-C)
USB 3.2 Gen1	4 (1x Type-C)	4 (1x Type-C)	4 (1x Type-C)	4 (1x Type-C)	4 (1x Type-C)	2	4
USB 2.0	4	4	–	–	–	4	–
COM Ports	–	2	2	2	2	2	2
Network (LAN)	Single LAN Intel 219 (1G)	Dual LAN Intel 225 (2.5G) Intel 219 (1G)	Dual LAN Intel 210 (1G) Intel 211 (1G)	Dual LAN Intel 225 (2.5G) Intel 225 (2.5G)	Dual LAN Intel 226LM (2.5G) Intel 226LM (2.5G)	Dual LAN Intel 226 (2.5G) Intel 219 (1G)	Dual LAN Intel 226 (2.5G) Intel 219 (1G)
AUDIO	Mic-Input, Line-Out (Realtek ALC662/897/888S)				Mic-Input, Line-Out (Realtek ALC888S)		
Optional Accessories	WLAN Kit: **WLN-M1**, Vertical Stand: **PS02**, Rackmount Kit: **PRM01** VGA Port: **PVG01**, Power Button Cable: **CXP01**, DIN-Rail Mount: **DIR01**, LTE/G-Kit: **WWN03**						
VESA Mount	optional **PV04**	supplied	supplied	supplied	supplied	supplied	supplied
Power Adap.	120 W / 19 V						180 W / 19 V
DC-IN Support	19V	12V+19V	19V	19V	19V	12V+19V	12V+19V

Product Images

DH610 / DH610S

DH670**), DH670V2 and DH770

DH810

DB860

DH610S

DH610

DH670(V2) and DH770

DH810

DB860

*) DH610S supports 3 displays, if equipped with VGA port (accessory PVG01)
**) DH670 supports Card Reader in the front panel (not shown in the picture)

Product Comparison: Shuttle XPC slim PCs with Intel 800 series chipset

MODEL	DH810	DB860	XH810	XB860G2
Processor Support	Intel Core Ultra Processors 2xx "Arrow Lake-S" Socket LGA1851, TDP max. 65W			
OS Support	Windows 11 & Linux – 64-bit			
Chipset	Intel H810 Supports Triple Display	Intel B860 Supports Quad Display	Intel H810 Supports Triple Display	Intel B860 Supports Quad Display
Memory	Supports max. 2x 48 GB DDR5-5600 SO-DIMM (262 Pins)			
PCIe Slots	–	–	–	1x PCIe Gen5 x16 1x PCIe Gen4 x1
Drive Bays	1x 2.5" bay supports SATA Raid 0+1	1x 2.5" bay supports SATA Raid 0+1	2x 2.5" bay (or 1x 3.5") supports SATA Raid 0+1	–
M.2 Slots for SSDs	1x M.2-2280 (PCIe X4, SATA)	1x M.2-2280 (PCIe X4, SATA)	1x M.2-2280 (PCIe X4, SATA) 1x M.2-2280 (PCIe X2, USB3.2)	3x M.2-2280 (PCIe X4) one also supports SATA
Front Panel Ports	2x USB 3.2 Gen 2 (1x Type-C) 1x USB 2.0 2x Audio Power-Button Power-LED, HDD-LED	4x USB 3.2 Gen 2 (1x Type-C) 2x Audio Power-Button Power-LED, HDD-LED	2x USB 3.2 Gen 1 (1x Type-C) 2x USB 2.0 2x Audio Power-Button Power-LED, HDD-LED	2x USB 3.2 Gen 1 (1x Type-C) 2x USB 2.0 2x Audio Power-Button Power-LED, HDD-LED
Back Panel Ports	HDMI 2.1 (8K) DisplayPort 1.4 USB4/DisplayPort (USB-C) 2x USB 3.2 Gen 1 (blue) 2x USB 2.0 2x Intel LAN (1G and 2.5G) 2x COM RS232 (1x RS422/485) DC input (supports 12V and 19V) Header for ext. power button	HDMI 2.1 (8K) HDMI 2.0 DisplayPort 1.4 USB4/DisplayPort (USB-C) 4x USB 3.2 Gen 2 (red) 2x Intel LAN (1G and 2.5G) 2x COM RS232 (1x RS422/485) DC input (supports 19.5V) Header for ext. power button	HDMI 2.1 (8K) HDMI 2.0a DisplayPort 1.4 2x USB 3.2 Gen 2 (red) 2x USB 2.0 2x Intel LAN (1G and 2.5G) 3x COM RS232 (1x RS422/485) DC input (supports 12V and 19V) Header for ext. power button	HDMI 2.1 (8K) HDMI 2.0a DisplayPort 1.4 2x USB 3.2 Gen 2 (red) 2x USB 3.2 Gen 1 (blue) 2x Intel LAN (1G and 2.5G) DC input (supports 19.5V) Header for ext. power button
Power Adap.	120 W / 19 V DC-Input supports 12V and 19V	180 W / 19.5 V DC-Input supports 12V and 19	120 W / 19 V DC-Input supports 12V and 19V	180 W / 19.5 V
Optional Accessories	Vertical stand (**PS02**) Power Button cable (**CXP01**) VGA-Port (**PVG01**) WLAN kit (**WLN-M1**) 4G kit (**WWN03**) DIN-Rail Kit (**DIR01**) Rack-Mount Kit (**PRM01**)	Vertical stand (**PS02**) Power Button cable (**CXP01**) VGA-Port (**PVG01**) WLAN kit (**WLN-M1**) 4G kit (**WWN03**) DIN-Rail Kit (**DIR01**) Rack-Mount Kit (**PRM01**)	Vertical stand (**PS01**) Power Button cable (**CXP01**) 3x COM Ports (**PCM31**) VGA-Port (**PVG01**) WLAN kit (**WLN-M1**) 4G/5G kit (**WWN04**)	Power Button cable (**CXP01**) VGA-Port (**PVG01**) WLAN kit (**WLN-M1**) 4G/5G kit (**WWN04**) Upgrade kit supports second power adapter (**PRC02**)
VESA Mount	included	included	included	included
Chassis Dimensions	19 x 16.5 x 4.3 cm (ca. 1.3 L)	19 x 16.5 x 4.3 cm (ca. 1.3 L)	23.8 x 20 x 7.25 cm (ca. 3,5 L)	23.7 x 20 x 9.5 cm (ca. 4,5 L)
Front View				
Back View				

SHUTTLE XPC SLIM BAREBONE DH810 — SPECIFICATIONS

CHASSIS	Slim PC with black chassis made of metal Dimensions: 190 x 165 x 43 mm (LWH) = 1.35-litre Weight: 1.3 kg net and 2.1 kg gross Two holes for Kensington Locks and numerous threaded holes (M3) on both sides of the chassis
OPERATING SYSTEM	This system comes without an operating system. It is compatible with Windows 11 and Linux (64-bit)
PROCESSOR SUPPORT	Processor Socket LGA1851 Supports Intel Core Ultra 200 series 9/7/5 processors Code name "Arrow Lake-S" Maximum supported processor power consumption (Base TDP) = 65 W Supports processors with integrated graphics only **[5]** Does not support the unlock-function of Intel K-Series processors. Up to 24 cores (8 Performance-cores and 16 Efficient-cores) Neural Processing Unit (NPU) with 13 TOPS AI-Performance
PROCESSOR COOLING	Efficient Heat-pipe processor cooling with two 70 mm fans on the upper side of the chassis
INTEGRATED GRAPHICS	The features of the integrated Intel graphics function with Xe cores depend on the processor type used. **[5]** The PC features these graphics outputs: - HDMI 2.1 supports 8K UHD with max. 7680x4320 Pixel at 60 Hz (4320p60) - 2x DisplayPort (1x as USB-C) supports 4K UHD with max. 4096x2160 Pixel at 60 Hz (2160p60) - optional one analog Sub-D/VGA port (in exchange for a COM port) **[4]** Supports up to three independent displays with the integrated graphics function DisplayPort and HDMI support multi-channel digital audio over the same cable.
MAINBOARD / CHIPSET	Mainboard in a Shuttle form factor proprietary design for the XPC DH810 Chipset/Southbridge: Intel® H810 The Northbridge is integrated in the processor. Solid Capacitors for sensitive areas provide excellent heat resistance for enhanced system durability
BIOS	AMI BIOS, SPI Interface, 32 MB Flash-EEPROM Supports Hardware Monitoring and Watchdog functionality Supports Firmware-TPM (fTPM) v2.0 **[9]** Supports boot up from external USB flash memory Supports Unified Extensible Firmware Interface (UEFI) Supports power on after power failure **[7]**
MEMORY SUPPORT	2x SO-DIMM slot with 262 pins Supports DDR5-5600 (PC5-44800) SDRAM at 1.1 V Supports Dual Channel mode Supports a maximum of 48 GB per DIMM, maximum total size: 96 GB Note: Supports two unbuffered DIMM modules (no ECC or registered)
DRIVE BAY	1x 6.35 cm / 2.5" storage bay supports one hard disk or SSD drive with SATA connector Device height: 12.5 mm (max.)
SATA CONNECTORS	1x Serial-ATA III, 6 Gb/s (600 MB/s) bandwidth With Serial-ATA power connector (onboard) Supports SATA RAID 0 and 1 (with 2.5" SSD drive and M.2 SSD card)
M.2-2280M SSD SLOT	The M.2 2280M slot provides the following interfaces: - PCI-Express Gen. 4.0 X4, supports NVMe - SATA v3.0 (max. 6 Gbps) It supports M.2 cards with a width of 22 mm and a length of 80 mm (type 2280) Supports M.2 SSDs with SATA or PCI-Express interface Supplied M.2 SSD heat sink Kit with thermal pads
M.2-2230E SLOT FOR WLAN CARDS	Interfaces: PCI-Express X1, USB 2.0 and CNVi Supports M.2 cards with a width of 22 mm and a length of 30 mm (type 2230) Supports WLAN expansion cards (optional Shuttle accessory: **WLN-M1**)

AUDIO	Audio Realtek® ALC888S High-Definition Audio Two analog audio connectors (3.5 mm) on the front panel: 1) 2-channel line-out (head-phones) 2) microphone input Digital multi-channel audio output: by HDMI and DisplayPort
DUAL 2.5G LAN CONTROLLER	On the back panel are two RJ45 network ports with status LEDs: 1) left: 2.5G LAN port (Intel 226 chip) supports 100 / 1.000 / 2.500 Mbps operation 2) right: 1.0G LAN port (Intel 219 chip) supports 10 / 100 / 1.000 Mbps operation Supports WAKE ON LAN (WOL) **[10]** Supports network boot by Preboot eXecution Environment (PXE)
FRONT PANEL CONNECTORS	Microphone input Audio Line-out (headphones) 1x USB 3.2 Gen 2 Type A (red) 1x USB 3.2 Gen 2 Type C supports 3A charging current 2x USB 2.0 Type A (black) Power button Power LED (blue) HDD LED (yellow)
BACK PANEL CONNECTORS	1x HDMI 2.1 supports 8K/60Hz **[1]** 1x DisplayPort (DP 1.4a) **[2]** 1x USB4 as USB-C port supports DP 1.4a, USB4 (20 Gbit/s) and 3A charging current Optional: 1x D-Sub VGA connector (Accessory **PVG01 [4]**) 2x USB 3.2 Gen 1 Type A (blue) 2x USB 2.0 Type A (black) 1x 2.5G LAN (RJ45, Intel i225) 1x 1.0G LAN (RJ45, Intel i219) 2x RS232 serial port, 9-pin D-Sub (5/12V, 1x RS422/RS485) **[3]** 1x DC-input connector for external power adapter (supports 12V and 19V) 1x 4-pin connector (2.54 mm pitch) supports: - external power on button - Clear CMOS function - +5V DC voltage for external components 2x perforation for optional Wireless LAN antennas
OTHER ONBOARD CONNECTORS	1x jumper JP1 for power-on-after-power-fail (hardware solution) **[7]** 1x analog VGA graphics header VGA1 (2x 10-pin, 1 mm pitch) **[4]** 2x serial interface (COM) occupied by back panel connectors 1x USB 2.0 (4-pin) for optional accessory WWN03 (LTE kit) 1x fan connector (4-pin) occupied by the cooling system 1x connector for CMOS battery (occupied)
POWER ADAPTER	External 120 W power adapter (fanless) Input: 100~240 V AC, 50/60 Hz Output: 19 V DC, 6.32 A, max. 120 W DC Connector: 5.5/2.5 mm (outer/inner diameter) AC mains cable: 3 pins, ca. 1.7 m length, with C5/C6 coupler (called "Mickey Mouse" or "Clover-leaf") for the power adapter and CEE-7/7 plug with earth-contact (type E+F) for the power outlet The DC-input of the computer supports an external power source with 19V±5% or 12V±5%.
SUPPLIED ACCESSORIES	Multi-language user guide (EN, DE, FR, ES, JP, KR, SC, TC) VESA mount for 75/100 mm standard (two metal brackets) Four screws M3 x 5 mm (screws together VESA mount and PC) Four screws M4 x 10 mm (to affix VESA mount on the PC) Four screws M3 x 4 mm (to mount a 2.5" storage device into the bay) Two screws M3 x 5 mm (silver colour, to mount two M.2 cards) M.2-2280 SSD heat sink kit with four screws and three thermal pads Driver DVD (Windows 11 - 64-bit) Serial ATA cable for 2.5" drive including power cable External 120 W power adapter with power cord Protection cap for CPU socket (do not use if heatpipe or fan is mounted) Heatsink compound

OPTIONAL ACCESSORIES	**PVG01:** optional D-Sub VGA video output **[4]** **WLN-M1:** WLAN module in M.2-2230 format supports WLAN-ax and Bluetooth with two external antennas. **WWN03:** LTE adapter kit with antennas, but without LTE card **[8]** **PS02:** Stand for vertical operation **CXP01:** adapter cable for external power button **PRM01:** 2U rack mount front plate for two Shuttle XPC slim PCs **DIR01:** DIN-Rail mounting kit
ENVIRONMENTAL SPECIFICATIONS	Operating temperature range: 0~50 °C **[6]** Relative humidity, non-condensing: 10~90 %
CERTIFICATIONS / COMPLIANCE	EMI: FCC, CE, BSMI, RCM, VCCI Safety: ETL, CB, BSMI Other: RoHS, Energy Star, ErP
CONFORMITY	This device is classed as a technical information equipment (ITE) in class B and is intended for use in living room and office. The CE-mark approves the conformity by the EU directives: (1) 2004/108/EC relating to electromagnetic compatibility (EMC), (2) 2006/95/EC relating to Electrical Equipment designed for use within certain voltage limits (LVD), (3) 2009/125/EC relating to ecodesign requirements for energy-related products (ErP)

[1] HDMI output supports DVI-D with optional adapter

[2] How to convert DisplayPort into HDMI/DVI
The DisplayPort output can be converted to HDMI or DVI by an additional, passive adapter cable. For example:
DELOCK 82590: 1 m, DisplayPort (male, 20p) to HDMI-A (male, 19p)
DELOCK 82435: 5 m, DisplayPort (male, 20p) to DVI-D (male, 24p)
The integrated graphics automatically detects the connected display and puts out the appropriate electric signal - either through DisplayPort (without an adapter) or HDMI/DVI (with an adapter).
However, a monitor with a DisplayPort connector cannot be connected to the HDMI port with a simple, passive adapter.

[3] Serial Ports
This PC features two serial RS232 ports with 9-pin D-Sub connectors at the back panel. The left COM port (COM1) can also be configured as RS422 and RS485 in BIOS.
Pin 9 of the D-Sub COM-Port is a multi-functional signal. Based on the Jumper JP2 configuration on the mainboard, it can be configured as Ring Indicator (RI) or external power supply with a voltage level of either 5 V or 12 V. Each COM port can be configured separately. The maximum current is 500 mA per connector.

[4] Optional D-Sub/VGA connector
The mainboard features one analog graphics port VGA1 on the mainboard. This signal can be lead to the outside as a 15-pin D-Sub VGA connector on the backpanel by using the optional adapter **PVG01**. However doing so means one serial port (COM) less can be used on the backpanel. The integrated graphics supports a maximum of three displays simultaneously.

[5] Intel processors without integrated graphics (ID ends with "F", e.g. Core Ultra 7 265**F**) are not compatible.

[6] Operating temperature
For high ambient temperatures over 40 °C we strongly recommend to use SSDs (supporting at least 70 °C) and rugged SO-DIMM memory modules with a temperature range of up to 95 °C.

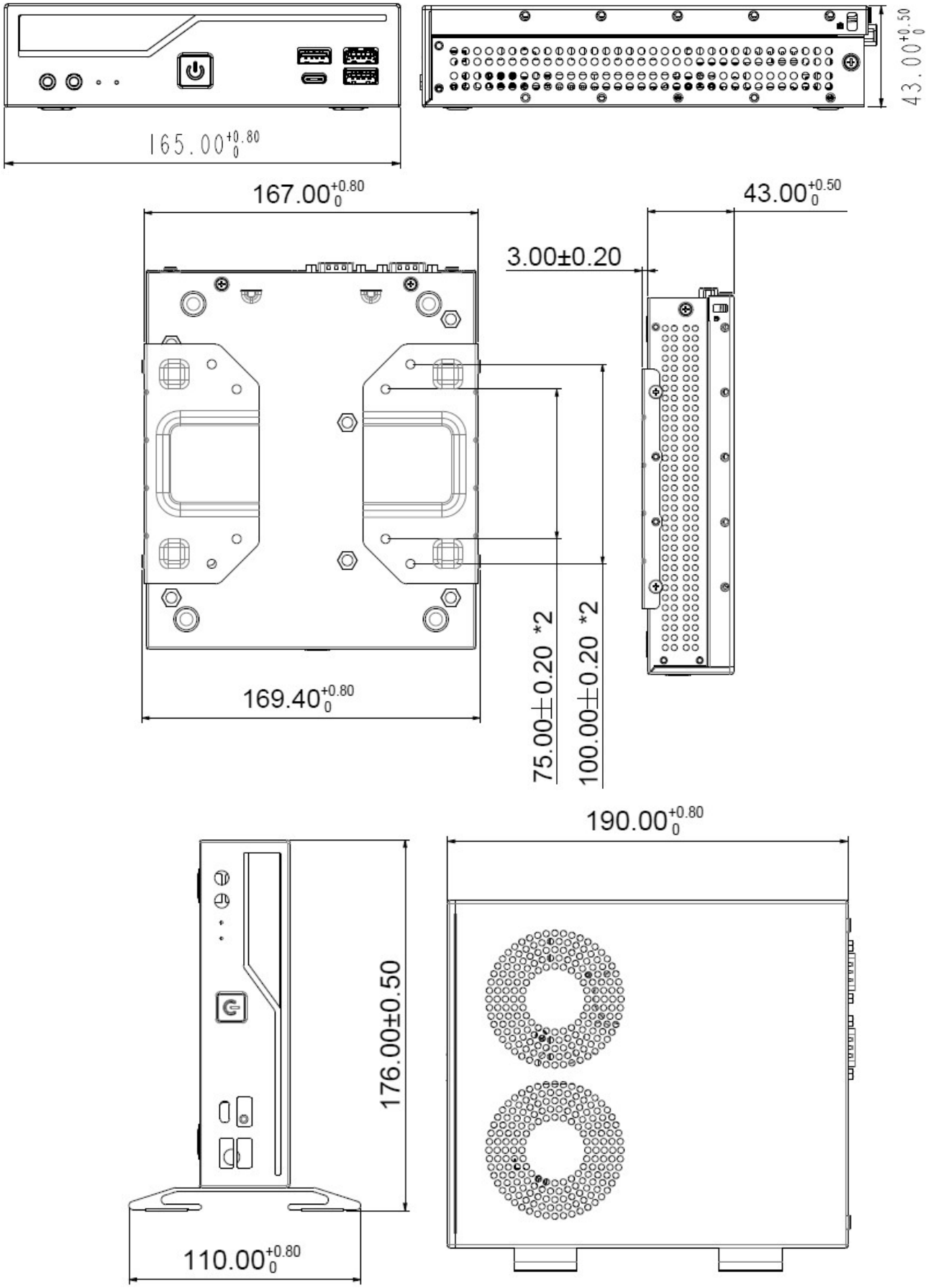
[7] Power on after power fail
The BIOS setup provides a "Power-On after Power Fail" function that can be found under "Power Management Configuration". As the name indicates, this function determines the PC's behaviour after power failure: (1) unconditional power on, (2) restore former status or (3) keep system turned off. As a matter of the nature of this function, it may fail after short power failures. This is why the DH810 also comes with a hardware-based solution. By removing Jumper JP1 (on the mainboard next to the power button) the system will start unconditionally once power is supplied.

[8] Optional Accessory WWN03 (LTE kit)
The Shuttle XPC accessory WWN03 allows this PC to be upgraded with an LTE/4G function for mobile network. The LTE card will occupy the 2.5" bay, so you will have to use an M.2 SSD as a mass storage device. The required LTE/4G card in M.2-3042 format and an activated Nano SIM card is not included in the scope of delivery.

[9] TPM Function
This product features Firmware-TPM (fTPM) v2.0. Besides this, it is prepared for a hardware TPM chip which can be fitted by factory on request, if required.

[10] Note on the Wake-on-LAN function
Summary: Please use the 2.5G network connection for the WOL function.
Explanation: This PC has two network connections (LAN ports):
(1) 1.0G (Intel 219 chip)
(2) 2.5G (Intel 226 chip)
The PC supports the Wake-on-LAN function (WOL) to start the switched-off computer (from S5 mode) via the network. The following settings can be found in the 'Advanced' BIOS setup:
(1) Wake Up by LAN = Enabled (this activates WOL)
(2) Power-On after Power-Fail = Power On by LAN
The second setting defines the behaviour after a power failure – in this case, the PC should not switch on immediately as soon as power is restored, but should wait for the power-on signal via the network connection. However, after a power failure, switching on via the network (WOL) only works via the 2.5G network port for technical reasons. Do not use the 1.0G network port for the WOL function if you expect that the PC's power supply could be interrupted.

Technical Drawings DH810



INTEL CORE ULTRA GEN. 2 DESKTOP PROCESSOR FAMILY

Socket LGA1851, Code Name "Arrow Lake-S" processor overview (Date: May 2025)
Each processor containing an NPU capable of upto 13 TOPS
Processors with a TDP of more than 65W and processors without graphics function (ID ends with "F") are not supported by DH810 (marked in red).

PROCESSOR	MODEL	P-CORES/ THREADS	P-CORES Base/Turbo2.0	E-CORES	E-CORES Base/Turbo2.0	SMART CACHE	BASE TDP	MEMORY SUPPORT	Intel® Graphics Xe Cores / Clock Rate
Core Ultra 9	**285K**	8 / 8	3.7 – 5.5 GHz	16	3.2 – 4.6 GHz	36 MB	**125 W**	DDR5-5600/6400	4 Cores, max. 2.00 GHz
	285	8 / 8	3.7 – 5.4 GHz	16	1.9 – 4.6 GHz	36 MB	65 W	DDR5-5600/6400	4 Cores, max. 2.00 GHz
	285T	8 / 8	1.4 – 5.3 GHz	16	1.2 – 4.6 GHz	36 MB	35 W	DDR5-5600/6400	4 Cores, max. 2.00 GHz
Core Ultra 7	**265K**	8 / 8	3.9 – 5.4 GHz	8	3.3 – 4.6 GHz	30 MB	**125 W**	DDR5-5600/6400	4 Cores, max. 2.00 GHz
	265KF	8 / 8	3.9 – 5.4 GHz	8	3.3 – 4.6 GHz	30 MB	**125 W**	DDR5-5600/6400	**None**
	265	8 / 8	2.4 – 5.2 GHz	8	1.8 – 4.6 GHz	30 MB	65 W	DDR5-5600/6400	4 Cores, max. 1.95 GHz
	265F	8 / 8	2.4 – 5.2 GHz	8	1.8 – 4.6 GHz	30 MB	65 W	DDR5-5600/6400	**None**
	265T	8 / 8	1.5 – 5.2 GHz	8	1.2 – 4.6 GHz	30 MB	35 W	DDR5-5600/6400	4 Cores, max. 1.95 GHz
Core Ultra 5	**245K**	6 / 6	4.2 – 5.2 GHz	8	3.6 – 4.6 GHz	24 MB	**125 W**	DDR5-5600/6400	4 Cores, max. 1.90 GHz
	245KF	6 / 6	4.2 – 5.2 GHz	8	3.6 – 4.6 GHz	24 MB	**125 W**	DDR5-5600/6400	**None**
	245	6 / 6	3.5 – 5.1 GHz	8	3.0 – 4.5 GHz	24 MB	65 W	DDR5-5600/6400	4 Cores, max. 1.90 GHz
	245T	6 / 6	2.5 – 5.1 GHz	8	1.9 – 4.5 GHz	24 MB	35 W	DDR5-5600/6400	4 Cores, max. 1.90 GHz
	235	6 / 6	3.4 – 5.0 GHz	8	2.9 – 4.4 GHz	24 MB	65 W	DDR5-5600/6400	3 Cores, max. 2.00 GHz
	235T	6 / 6	2.2 – 5.0 GHz	8	1.6 – 4.4 GHz	24 MB	35 W	DDR5-5600/6400	3 Cores, max. 2.00 GHz
	225	4 / 4	3.3 – 4.9 GHz	4	1.8 – 4.4 GHz	20 MB	65 W	DDR5-5600/6400	2 Cores, max. 1.80 GHz
	225F	4 / 4	3.3 – 4.9 GHz	4	2.7 – 4.4 GHz	20 MB	65 W	DDR5-5600/6400	**None**
	225T	4 / 4	2.5 – 4.9 GHz	4	2.7 – 4.4 GHz	20 MB	35 W	DDR5-5600/6400	2 Cores, max. 1.80 GHz

K = unlocked, T = Power optimized lifestyle, F = without integrated graphics, Base TDP = Base Thermal Design Power (max. Base Power Consumption).

Note: The Shuttle XPC slim Barebone **DH810** does not support the Unlock-function of Intel **K-Series** processors.
P-Cores: Performance-Cores (without Hyper-Threading/SMT support), **E-Cores:** Efficient-Cores
Core Clock: the listed core frequency ranges from Base Frequncy to Turbo Boost 2.0 Frequency (Turbo Boost 3.0/TVB Frequency is not mentioned here)
Base TDP: Processor Base Power dissipation that the processor is validated to not exceed at Base Frequency (Max. Turbo Power is not mentioned here)
Please refer to the support list for detailed processor support information at global.shuttle.com.